# 2.5V / 3.3V Differential 2 x 2 Crosspoint Switch with CML Outputs Clock/Data Buffer/Translator

### Multi-Level Inputs w/ Internal Termination

#### Description

The NB7L72M is a high bandwidth, low voltage, fully differential 2 x 2 crosspoint switch with CML outputs. The NB7L72M design is optimized for low skew and minimal jitter as it produces two identical copies of Clock or Data operating up to 7 GHz or 10 Gb/s, respectively. As such, the NB7L72M is ideal for SONET, GigE, Fiber Channel, Backplane and other clock/data distribution applications.

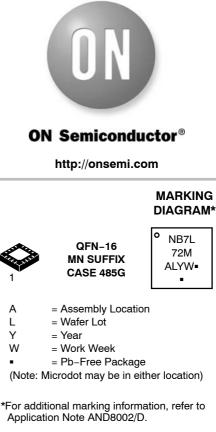
The differential IN/ $\overline{IN}$  inputs incorporate internal 50  $\Omega$  termination resistors and will accept LVPECL, CML, or LVDS logic levels (see Figure 11). The 16 mA differential CML outputs provide matching internal 50  $\Omega$  terminations and produce 400 mV output swings when externally terminated with a 50  $\Omega$  resistor to V<sub>CC</sub> (see Figure 9).

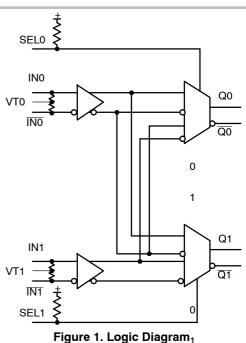
The NB7L72M is the 2.5 V/3.3 V version of the and NB7V72M and is offered in a low profile 3x3 mm 16-pin QFN package. Application notes, models, and support documentation are available at www.onsemi.com.

The NB7L72M is a member of the GigaComm<sup>™</sup> family of high performance clock products.

#### Features

- Maximum Input Data Rate > 10 Gb/s
- Data Dependent Jitter < 10 ps pk-pk
- Maximum Input Clock Frequency > 7 GHz
- Random Clock Jitter < 0.5 ps RMS, Max
- 150 ps Typical Propagation Delay
- 30 ps Typical Rise and Fall Times
- Differential CML Outputs, 400 mV peak-to-peak, typical
- Operating Range:  $V_{CC} = 2.375$  V to 3.6 V with GND = 0 V
- Internal 50  $\Omega$  Input Termination Resistors
- QFN-16 Package, 3mm x 3mm
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices





### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

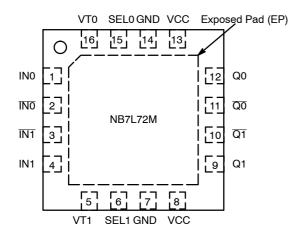


Figure 2. Pin Configuration (Top View)

### Table 1. INPUT/OUTPUT SELECT TRUTH TABLE

SEL0*	SEL1*	Q0	Q1
L	L	INO	IN0
L	Н	INO	IN1
Н	L	IN1	IN0
Н	Н	IN1	IN1

\*Defaults HIGH when left open

Pin	Name	I/O	Description
1	IN0	LVPECL, CML, LVDS Input	Noninverted Differential Input. (Note 1)
2	ĪN0	LVPECL, CML, LVDS Input	Inverted Differential Input. (Note 1)
3	ĪN1	LVPECL, CML, LVDS Input	Inverted Differential Input. (Note 1)
4	IN1	LVPECL, CML, LVDS Input	Noninverted Differential Input. (Note 1)
5	VT1	-	Internal 50 $\Omega$ Termination Pin for IN1 and IN1.
6	SEL1	LVCMOS Input	Input Select logic pin for IN0 or IN1 Inputs to Q1 output. See Table 1, Input/Output Select Truth Table; pin defaults HIGH when left open.
7	GND		Negative Supply Voltage
8	VCC	-	Positive Supply Voltage
9	Q1	CML Output	Noninverted Differential Output. (Note 1)
10	Q1	CML Output	Inverted Differential Output. (Note 1)
11	<u>Q0</u>	CML Output	Inverted Differential Output. (Note 1)
12	Q0	CML Output	Noninverted Differential Output. (Note 1)
13	VCC	-	Positive Supply Voltage
14	GND	-	Negative Supply Voltage
15	SEL0	LVCMOS Input	Input Select logic pin for IN0 or IN1 Inputs to Q0 output. See Table 1, Input/Output Select Truth Table; pin defaults HIGH when left open.
16	VT0	_	Internal 50 $\Omega$ Termination Pin for IN0 and $\overline{\text{IN0}}$
-	EP	-	The Exposed Pad (EP) on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat–sinking conduit. The pad is electrically connected to the die, and is recommended to be electrically and thermally connected to GND on the PC board.

1. In the differential configuration when the input termination pins (VT0, VT1) are connected to a common termination voltage or left open, and if no signal is applied on INx/INx input, then the device will be susceptible to self-oscillation. 2. All VCC and GND pins must be externally connected to a power supply for proper operation.

#### **Table 3. ATTRIBUTES**

Characteristi	Characteristics		
ESD Protection Human Body Model Machine Model		> 4 kV > 200 V	
R <sub>PU</sub> – Input Pullup Resistor	75 kΩ		
Moisture Sensitivity (Note 3)	QFN-16	Level 1	
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
Transistor Count	212		
Meets or exceeds JEDEC Spec EIA/	IESD78 IC Latchup Test		

3. For additional information, see Application Note AND8003/D.

#### **Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V		4.0	V
V <sub>IN</sub>	Positive Input Voltage	GND = 0 V		–0.5 to V <sub>CC</sub> +0.5	V
V <sub>INPP</sub>	Differential Input Voltage  IN - IN			1.89	V
I <sub>IN</sub>	Input Current Through $R_T$ (50 $\Omega$ Resistor)			±40	mA
I <sub>OUT</sub>	Output Current Through $R_T$ (50 $\Omega$ Resistor)			±40	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient) (Note 4)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W °C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction-to-Case) (Note 4)		QFN-16	4	°C/W
T <sub>sol</sub>	Wave Solder Pb-Fre	e		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
4. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS	<b>Iulti-Level Inputs</b> $V_{CC}$ = 2.375 V to 3.6 V, GND = 0 V, $T_A$ = -40°C to +85°C	(Note 5)
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Symbol	Characteristic		Min	Тур	Max	Unit
POWER	SUPPLY CURRENT					
V <sub>CC</sub>	Power Supply Voltage	V <sub>CC</sub> = 2.5 V V <sub>CC</sub> = 3.3 V	2.375 3.0	2.5 3.3	2.625 3.6	V
I <sub>CC</sub>	Power Supply Current (Inputs and Outputs Open)		80	135	175	mA

**CML OUTPUTS** 

V <sub>OH</sub>	Output HIGH Voltage (Note 6)	V <sub>CC</sub> = 3.3 V V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> – 40 3260 2460	V <sub>CC</sub> – 20 3280 2480	V <sub>CC</sub> 3300 2500	mV
V <sub>OL</sub>	Output LOW Voltage (Note 6)	V <sub>CC</sub> = 3.3 V V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> – 650 2650 V <sub>CC</sub> – 600 1900	$V_{CC} - 500 \\ 2800 \\ V_{CC} - 500 \\ 2000$	$V_{CC} - 400 \\ 2900 \\ V_{CC} - 350 \\ 2150$	mV

DIFFERENTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Note 7) (Figures 5 and 7)

V <sub>th</sub>	Input Threshold Reference Voltage Range (Note 8)	1050	V <sub>CC</sub> – 100	mV
V <sub>IH</sub>	Single-Ended Input HIGH Voltage	V <sub>th</sub> + 100	V <sub>CC</sub>	mV
V <sub>IL</sub>	Single-Ended Input LOW Voltage	GND	V <sub>th</sub> – 100	mV
V <sub>ISE</sub>	Single-Ended Input Voltage (VIH - VIL)	200	2800	mV

DIFFERENTIAL DATA/CLOCK INPUTS DRIVEN DIFFERENTIALLY (Figures 6 and 8) (Note 9)

V <sub>IHD</sub>	Differential Input HIGH Voltage (INn, INn)	1100	V <sub>CC</sub>	mV
V <sub>ILD</sub>	Differential Input LOW Voltage (INn, INn)	GND	V <sub>CC</sub> – 100	mV
V <sub>ID</sub>	Differential Input Voltage (INn, INn) (V <sub>IHD</sub> - V <sub>ILD</sub> )	100	1200	mV
V <sub>CMR</sub>	Input Common Mode Range (Differential Configuration, Note 10) (Figure 9)	950	V <sub>CC</sub> – 50	mV
I <sub>IH</sub>	Input HIGH Current INn, INn (VTIN/VTIN Open)	-150	150	μΑ
IIL	Input LOW Current INn, INn (VTIN/VTIN Open)	-150	150	μA

CONTROL INPUTS (SEL0, SEL1)

V <sub>IH</sub>	Input HIGH Voltage for Control Pins	2.0		V <sub>CC</sub>	mV		
V <sub>IL</sub>	Input LOW Voltage for Control Pins	GND		0.8	mV		
I <sub>IH</sub>	Input HIGH Current	-150		150	μΑ		
IIL	Input LOW Current	-150		150	μΑ		
TERMIN	TERMINATION RESISTORS						

**R**<sub>TIN</sub> Internal Input Termination Resistor 40 50 60 Ω 60 R<sub>TOUT</sub> Internal Output Termination Resistor 40 50 Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with  $V_{CC}$ .

6. CML outputs loaded with 50  $\Omega$  to V<sub>CC</sub> for proper operation.

V<sub>th</sub>, V<sub>IH</sub>, V<sub>IL</sub>, and V<sub>ISE</sub> parameters must be complied with simultaneously.
 V<sub>th</sub> is applied to the complementary input when operating in single–ended mode.

9. VIHD, VILD, VID and VCMR parameters must be complied with simultaneously.

10. V<sub>CMR</sub> min varies 1:1 with GND, V<sub>CMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>CMR</sub> range is referenced to the most positive side of the differential input signal.

Symbol	Characteristic		Min	Тур	Max	Unit
f <sub>MAX</sub>		i ≥ 250 mV ≥ 200 mV	7.0 8.5			GHz
f <sub>DATAMAX</sub>	Maximum Operating Data Rate (PRBS23)		10			Gbps
V <sub>OUTPP</sub>	Output Voltage Amplitude (@ V <sub>INPPmin</sub> ) f <sub>it</sub> (See Figures 3 and 10, Note 12)	ר≤8.5 GHz	200	400		mV
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Differential Outputs, @ 1GHz, Measured at Differential Cross-point	INn/INn to Qn/Qn SELn to Qn/Qn	110	150	180	ps
t <sub>PLH</sub> TC	Propagation Delay Temperature Coefficient			50		∆fs/°C
t <sub>SKEW</sub>	Output-to-Output Skew (within device) (Note 13) Device-to-Device Skew (t <sub>pdmax</sub> – t <sub>pdmin</sub> )				10 20	ps
t <sub>DC</sub>	Output Clock Duty Cycle (Reference Duty Cycle = 50%) f <sub>ir</sub>	n ≤ 8.5GHz	45	50	55	%
t <sub>jitter</sub>	RJ – Output Random Jitter (Note 14) fin DJ – Deterministic Jitter (Note 15)	≤ 8.5 GHz ≤ 10 Gbps		0.2	0.5 10	ps RMS ps pk–pk
V <sub>INPP</sub>	Input Voltage Swing (Differential Configuration) (Note 16)		100		1200	mV
t <sub>r,</sub> , t <sub>f</sub>	Output Rise/Fall Times @ 1 GHz (20% - 80%),	Q, <u>Q</u>	25	30	50	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured using a 400 mV source, 50% duty cycle clock source. All output loading with external 50  $\Omega$  to V<sub>CC</sub>. Input edge rates  $\geq$  40 ps (20% - 80%).

12. Output voltage swing is a single-ended measurement operating in differential mode.

13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from cross-point of the inputs to the cross-point of the outputs.

14. Additive RMS jitter with 50% duty cycle clock signal.

15. Additive Peak-to-Peak data dependent jitter with input NRZ data at PRBS23.

16. Input voltage swing is a single-ended measurement operating in differential mode.

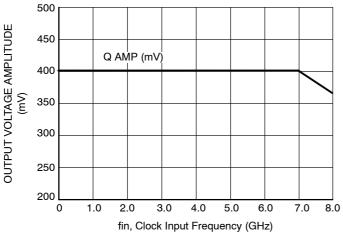


Figure 3. CLOCK Output Voltage Amplitude (V<sub>OUTPP</sub>) vs. Input Frequency (f<sub>in</sub>) at Ambient Temperature (Typ)

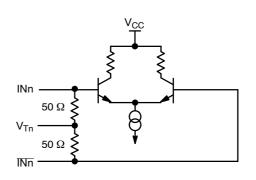
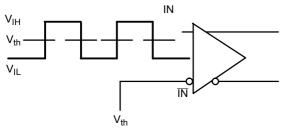
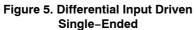
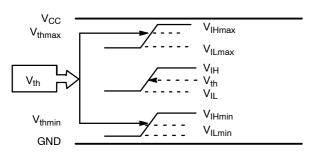


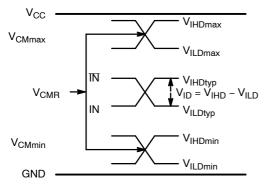
Figure 4. Input Structure



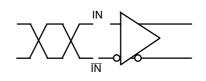




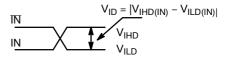














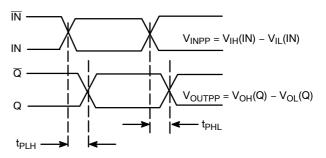


Figure 10. AC Reference Measurement

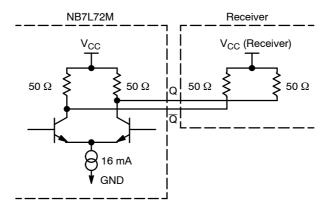


Figure 11. Typical CML Output Structure and Termination

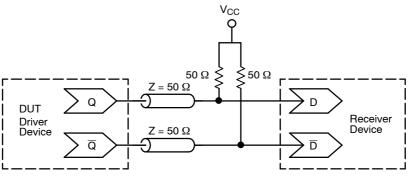
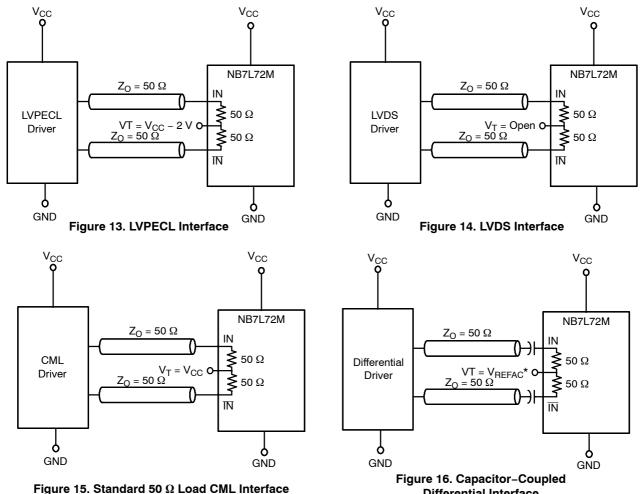


Figure 12. Typical Termination for CML Output Driver and Device Evaluation



Differential Interface

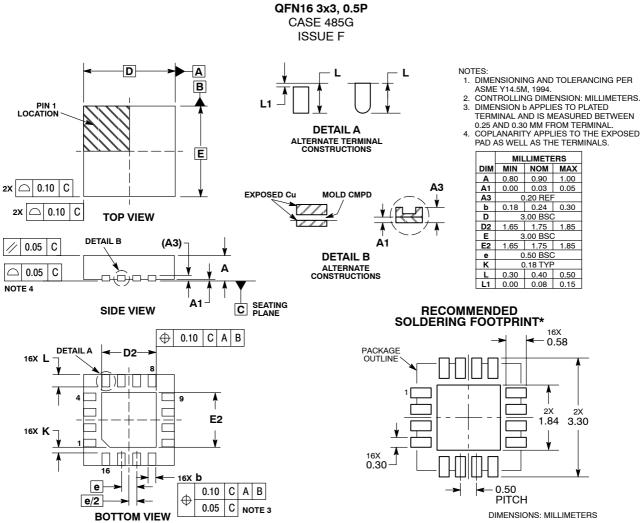
(VT Connected to External V<sub>REFAC</sub>)  $*V_{REFAC}$  bypassed to ground with a 0.01  $\mu$ F capacitor

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NB7L72MMNG	QFN-16 (Pb-free)	123 Units / Rail
NB7L72MMNTXG	QFN-16 (Pb-free)	3000 / Tape & Reel
NB7L72MMNHTBG	QFN-16 (Pb-free)	100 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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